

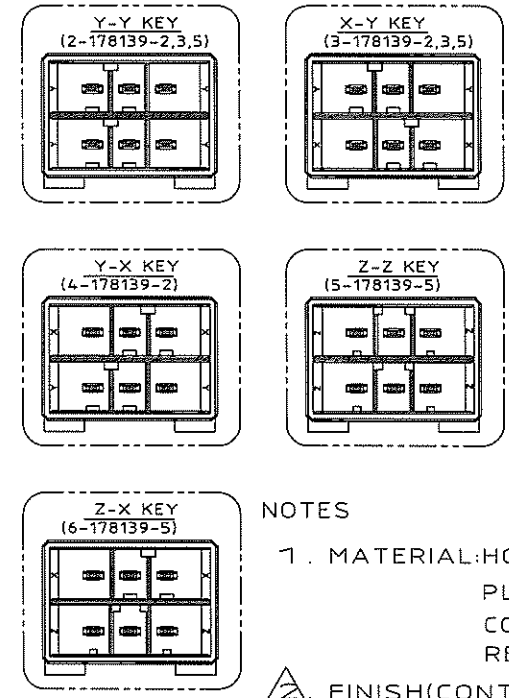
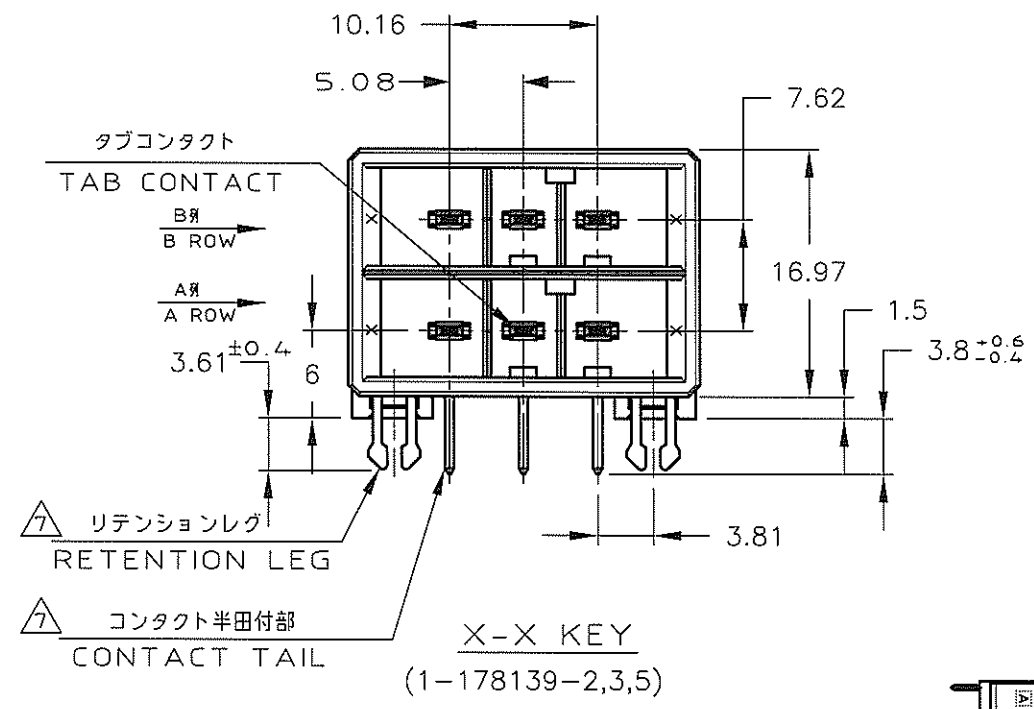
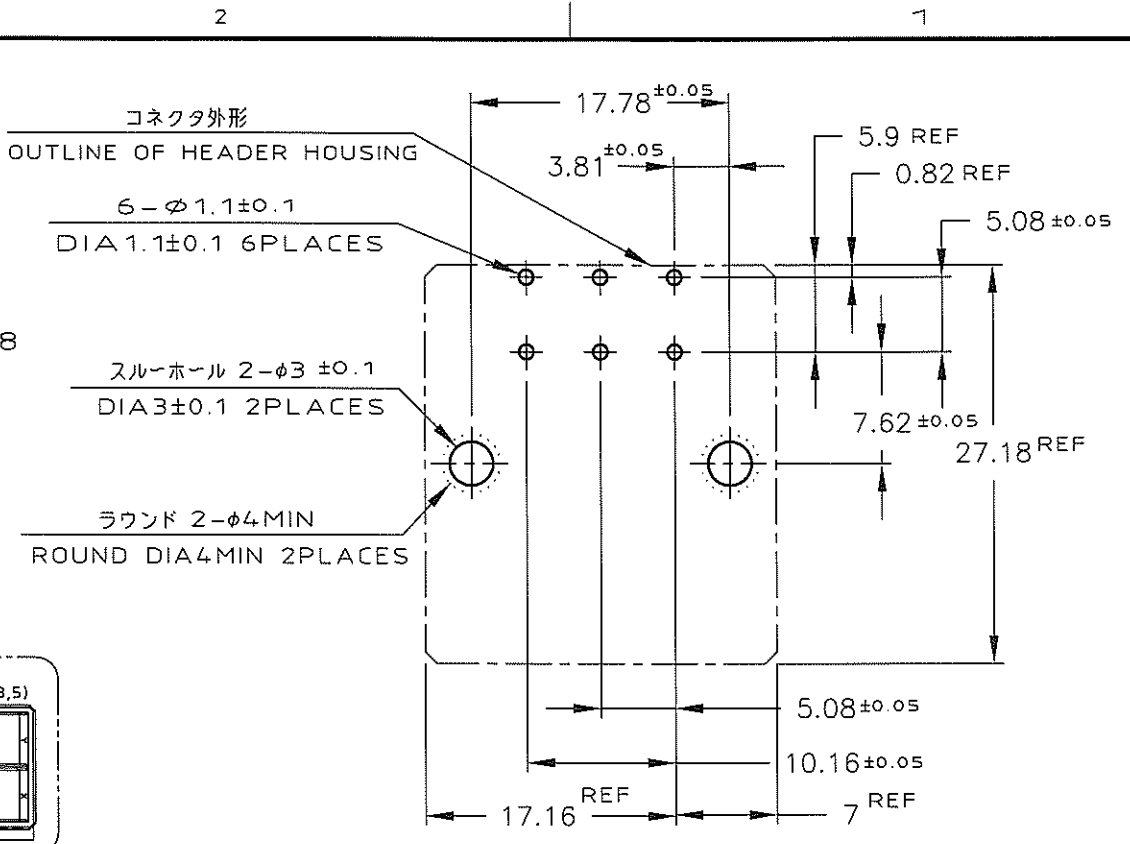
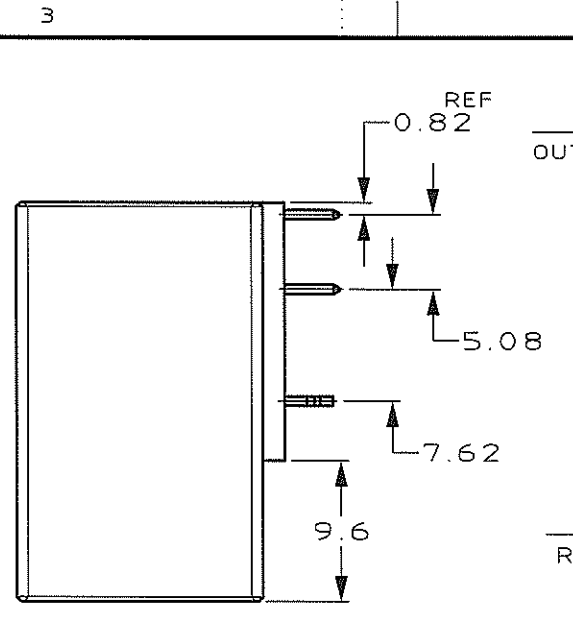
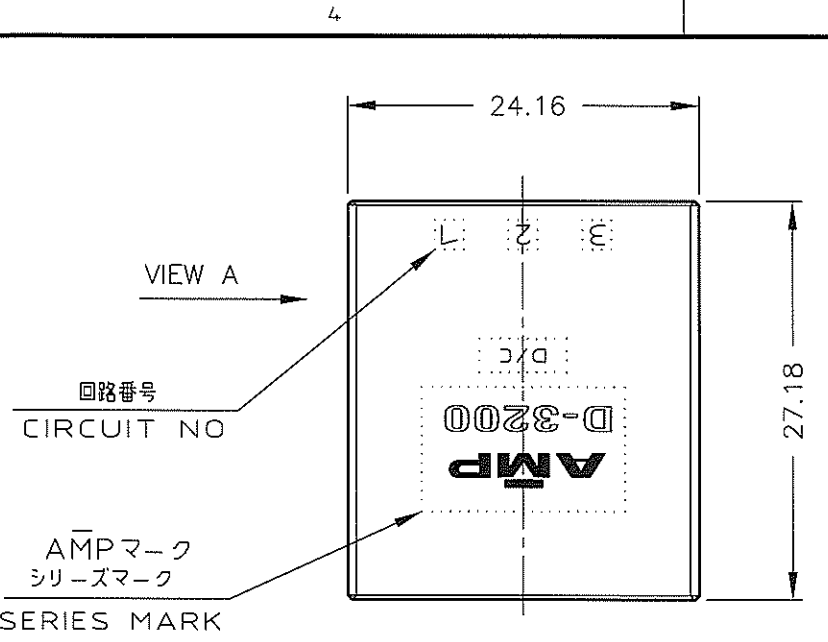
NUMBER 178139

3rd ANGLE PROJECTION

METRIC

DIMENSIONS IN MILLIMETERS. DO NOT SCALE PRINT

PRINT DIST



NOTES

- MATERIAL: HOUSING: GLASS FILLED THERMO PLASTIC, POLYESTER
CONTACT: COPPER ALLOY
RETENTION LEG: COPPER ALLOY
- FINISH (CONTACT AREA): 0.38 μm MIN GOLD PLATING OVER Ni PLATING
- FINISH (CONTACT AREA): 0.76 μm MIN GOLD PLATING OVER Ni PLATING
- FINISH (CONTACT AREA): 2.0 μm MIN TIN PLATED OVER NICKEL
- FINISH (RETENTION LEG): TIN LEAD PLATED (CONTACT TAIL) OVER NICKEL
- PRODUCT SPEC: 108-5349
- FINISH (RETENTION LEG): TIN PLATED (CONTACT TAIL) OVER NICKEL

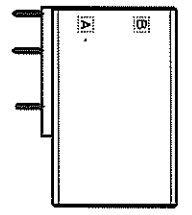
注記

- 材料: ハウジング: ガラス入り熱可塑性ポリエステル樹脂
コンタクト: 銅合金
リテンションレグ: 銅合金
- めっき: コンタクト: 全面Ni下地
接触部: 0.38 μm MIN 金めっき
- めっき: コンタクト: 全面Ni下地
接触部: 0.76 μm MIN 金めっき
- めっき: コンタクト: 全面Ni下地
接触部: 2.0 μm MIN スズめっき
- めっき: リテンションレグとコンタクト半田付部
ニッケル下地の土に半田めっき
- 製品規格: 108-5349
- めっき: リテンションレグとコンタクト半田付部
ニッケル下地の土にスズめっき

推奨基板取付け穴寸法
PC 基板厚: 1.6 ± 0.1
(非累積公差)
(コネクタ搭載面)

RECOMEND PC BOARD HOLE PATTERN
PC BOARD THICKNESS: 1.6 ± 0.1
(NOT ACCUMULATE TOLERANCE)
(CONNECTOR MOUNT SIDE)

7	4	1,2,3,5,6-178139-5
7	3	1,2,3-178139-3
7	2	1,2,3,4-178139-2
(FINISH)		製品番号 (PART NO.)



VIEW A (SCALE: 1:1)

				WIRE RANGE		INSULATION DIA		NAME			
				mm ² (AWG -)		mmφ		6 POS SINGLE ROW			
				MATERIAL SEE NOTE 注記参照		FINISH SEE NOTE 注記参照		HORIZONTAL HDR ASS'Y FOR DYNAMIC D-3200			
				E3 REVISED PER ECO-11-005030 RK HMR 14APR 11		DR. K.IKEDA 20/MAR/95		DE. K.IKEDA 20/MAR/95		一般公差 (GENERAL TOLERANCE)	
				LTR REVISION RECORD DR CHK DATE		CHK. S.MANABE 23/MAR/95		APP. S.MANABE 23/MAR/95		SIZE LOC NUMBER	
								A3 J		C-178139	
								SCALE 2-1		REV. E3 SHEET 1 OF 1	



Mouser Electronics

Authorized Distributor

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[TE Connectivity:](#)

[2-178139-2](#)